

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6936181"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 08:28
L3	36	"6517995"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 09:03
L4	3	"6730617"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 09:51
L5	68	infrared near9 conventional\$3 near9 (heat\$3 thermal\$4) near3 (cure curing cross\$1link\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 09:58
L6	57	(integrated printed) near3 (circuit board) and test\$3 near3 "in situ"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 10:01
L7	21	(integrated printed) near3 (circuit board) same test\$3 near3 "in situ"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 10:00
L8	2	(integrated printed) near3 (circuit board) and test\$3 near3 "in situ" near9 (substrate array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 10:14
L9	0	electroless same test\$3 near3 "in situ" near9 (substrate array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 10:03

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L10	0	electroless same test\$3 near3 "in situ"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 10:03
L11	2	electroless and test\$3 near3 "in situ"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 10:03
L12	2	"6545498".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/19 10:06
S1	2	"20050142345"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 19:40
S2	69	(JAYARAMAN near3 SAIKUMAR).in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 19:17
S3	29396	intel.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 10:34
S4	13545	(INTEL near3 CORPORATION).as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 10:35
S5	61799	imprint\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:23

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S6	4113	S5 and ((printed near3 board) PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:24
S7	5343	S5 and ((printed near3 board) PWB (cell\$4 near phone) (personal near3 digital) PDA (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:12
S8	51	S7 and ((partial\$4 near3 (cross\$1link\$3 curing cure)) pre\$1curing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:17
S9	2	S7 and (stack multiple plurality first second upper top) near3 (coat\$3 layer film) near9 ((partial\$4 near3 (cross\$1link\$3 curing cure)) pre\$1curing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:20
S10	44135	(imprint\$3 stamp\$3 emboss\$3 impress\$3) and ((printed near3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:33
S11	4	(stack multiple plurality first second upper top multi\$1layer\$4) near9 ((partial\$4 near3 (cross\$1link\$3 curing cure\$1)) pre\$1curing) near9 (imprint\$3 stamp\$3 emboss\$3 impress\$3) and ((printed near3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:35
S12	4	(stack multiple plurality first second upper top multi\$1layer\$4) near20 ((partial\$4 near3 (cross\$1link\$3 curing cure\$1)) pre\$1curing) near9 (imprint\$3 stamp\$3 emboss\$3 impress\$3) and ((printed near3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:35

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S13	5	(stack multiple plurality first second upper top multi\$1layer\$4) near9 ((partial\$4 near3 (cross\$1link\$3 curing cure\$1)) pre\$1curing) near20 (imprint\$3 stamp\$3 emboss\$3 impress\$3) and ((printed near3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:38
S14	24	(stack multiple plurality first second upper top multi\$1layer\$4 (two near3 layer)) near9 ((partial\$4 near3 (cross\$1link\$3 curing cure\$1)) pre\$1cur\$3 (green near3 state)) near20 (imprint\$3 stamp\$3 emboss\$3 impress\$3) and ((printed near3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:42
S15	19	S14 not S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:40
S16	5	(stack multiple plurality first second upper top multi\$1layer\$4 (two near3 layer)) near9 ((partial\$4 near3 (cross\$1link\$3 curing cure\$1)) pre\$1cure pre\$1curing (green near3 state)) near20 (imprint\$3 stamp\$3 emboss\$3 impress\$3) and ((printed near3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:46
S17	5	(stack multiple plurality first second upper top multi\$1layer\$4 (two near3 layer)) near9 ((partial\$4 near3 (thermose\$4 harden\$3 stiffen\$4 cross\$1link\$3 curing cure\$1)) pre\$1cure pre\$1curing (green near3 state)) near20 (imprint\$3 stamp\$3 emboss\$3 impress\$3) and ((printed near3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 11:46

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S18	167	(stack multiple plurality first second upper top multi\$1layer\$4 (two near\$3 layer)) near\$9 ((partial\$4 near\$3 (thermose\$4 harden\$3 stiffen\$4 cross\$1link\$3 curing cure\$1)) pre\$1cure pre\$1curing (green near\$3 state)) and (imprint\$3 stamp\$3 emboss\$3 impress\$3) and ((printed near\$3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 12:51
S19	7	((partial\$4 near\$3 (thermose\$4 harden\$3 stiffen\$4 cross\$1link\$3 curing cure\$1)) pre\$1cure pre\$1curing (green near\$3 state)) near\$9 (complet\$3 full\$3) near\$20 (imprint\$3 stamp\$3 emboss\$3 impress\$3) and ((printed near\$3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 12:52
S20	7	((partial\$4 near\$3 (thermose\$4 harden\$3 stiffen\$4 cross\$1link\$3 curing cure\$1)) pre\$1cure pre\$1curing (green near\$3 state)) near\$20 (imprint\$3 stamp\$3 emboss\$3 impress\$3) near\$9 (complet\$3 full\$3) and ((printed near\$3 board) PCB PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 13:14
S21	20	((partial\$4 near\$3 (thermoset\$4 harden\$3 stiffen\$4 cross\$1link\$3 curing cure\$1)) pre\$1cure pre\$1curing A-stage green) near\$20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) near\$9 (complet\$3 full\$3) and (((printed integrated) near\$3 (circuit board)) PCB IC PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:21
S22	2077	first near\$3 (coat\$3 film layer) near\$20 (second top) near\$20 (coat\$3 film layer) near\$20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:23
S23	4	stack\$3 near\$20 (coat\$3 film layer) near\$20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) near\$9 (complet\$3 full\$3) and (((printed integrated) near\$3 (circuit board)) PCB IC PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:30

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S24	1	stack\$3 near3 (coat\$3 film layer) near20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) near9 (complet\$3 full\$3) and (((printed integrated) near3 (circuit board)) PCB IC PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:24
S25	9	(stack\$3 multiple plurality two first second) near9 (insulati\$4 dielectric\$4 encapsulat\$4) near20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) near9 (complet\$3 full\$3) and (((printed integrated) near3 (circuit board)) PCB IC PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:34
S26	628	(stack\$3 multiple plurality two first second) near9 (insulati\$4 dielectric\$4 encapsulat\$4) near20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) and (((printed integrated) near3 (circuit board)) PCB IC PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:35
S27	233	(stack\$3 multiple plurality two first second) near3 (insulati\$4 dielectric\$4 encapsulat\$4) near9 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) and (((printed integrated) near3 (circuit board)) PCB IC PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:37
S28	1	S3 and S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:35
S29	398	S3 and (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) and (((printed integrated) near3 (circuit board)) PCB IC PWB (electrical\$3 near contact\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:36
S30	1	(stack\$3 multiple plurality two first second) near3 (insulati\$4 dielectric\$4 encapsulat\$4) near9 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:37

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S31	173	(stack\$3 multiple plurality two first second) near3 (insulati\$4 dielectric\$4 encapsulat\$4) near9 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) and (((printed integrated) near3 (circuit board)) PCB IC PWB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:39
S32	71	(stack\$3 multiple plurality two first second) near3 (insulati\$4 dielectric\$4 encapsulat\$4) near9 (coat\$3 layer film) near20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) and (((printed integrated) near3 (circuit board)) PCB IC PWB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:39
S33	64	(stack\$3 multiple plurality two first second) near3 (insulati\$4 dielectric\$4 encapsulat\$4) near3 (coat\$3 layer film) near20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3) and (((printed integrated) near3 (circuit board)) PCB IC PWB)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:50
S34	41	damas\$8 near20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:49
S35	600	(stack\$3 multiple plurality two first second) near3 pattern\$4 near3 (coat\$3 layer film) near20 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:51
S36	535	(stack\$3 multiple plurality two first second) near3 pattern\$4 near3 (coat\$3 layer film) near9 (imprint\$3 micro\$1stamp\$3 stamp\$3 emboss\$3 impress\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:52
S37	253	(stack\$3 multiple plurality two first second) near3 pattern\$4 near3 (coat\$3 layer film) near9 (imprint\$3 micro\$1stamp\$3 stamp\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:53

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S38	43	(stack\$3 multiple plurality) near3 pattern\$4 near3 (coat\$3 layer film) near9 (imprint\$3 micro\$1stamp\$3 stamp\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/12 14:54
S39	2	"6517995".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 19:17
S40	202	thermal\$4 near3 (curing cure cross\$1link\$3) near9 infra\$1red	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 19:41
S41	304	thermal\$4 near3 (curing cure cross\$1link\$3) near9 (infra\$1red IR)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 19:41
S42	38	thermal\$4 near (curing cure cross\$1link\$3) near (infra\$1red IR)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 19:42
S43	90	thermal\$4 near (curing cure cross\$1link\$3) near3 (infra\$1red IR)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 19:42